

# TSD80R500S1

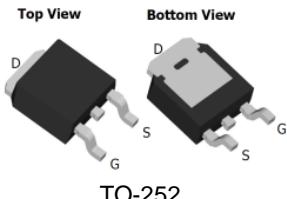
## 800V 10.5A N-Channel SJ-MOSFET

### General Description

Truesemi SJ-FET is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

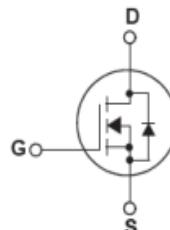
This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.

SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency.



### Features

- 850V @ $T_J = 150\text{ }^{\circ}\text{C}$
- Typ.  $R_{DS(on)} = 0.46\Omega$
- Ultra Low gate charge (typ.  $Q_g = 13\text{nC}$ )
- 100% avalanche tested



### Absolute Maximum Ratings

Symbol	Parameter	Value	Unit
$V_{DSS}$	Drain-Source Voltage	800	V
$I_D$	Drain Current -Continuous ( $TC = 25\text{ }^{\circ}\text{C}$ ) -Continuous ( $TC = 100\text{ }^{\circ}\text{C}$ )	10.5* 6.7*	A
$I_{DM}$	Drain Current – Pulsed (Note 1)	30*	A
$V_{GSS}$	Gate-Source voltage	$\pm 30$	V
$E_{AS}$	Single Pulsed Avalanche Energy (Note 2)	210	mJ
$I_{AR}$	Avalanche Current (Note 1)	1.8	A
$E_{AR}$	Repetitive Avalanche Energy (Note 1)	0.32	mJ
$dv/dt$	Peak Diode Recovery $dv/dt$ (Note 3)	15	V/ns
$P_D$	Power Dissipation ( $TC = 25\text{ }^{\circ}\text{C}$ )	83	W
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^{\circ}\text{C}$
$T_L$	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds	300	$^{\circ}\text{C}$

\* Drain current limited by maximum junction temperature.

### Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.5	$^{\circ}\text{C}/\text{W}$
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5	$^{\circ}\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62	$^{\circ}\text{C}/\text{W}$

## Electrical Characteristics TC = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Off Characteristics						
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	800	--	--	V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^\circ C$	--	850	--	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu A$ , Referenced to $25^\circ C$	--	0.6	--	V/°C
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 800V, V_{GS} = 0V, -T_J = 150^\circ C$	--	-- 10	1	$\mu A$ $\mu A$
$I_{GSSF}$	Gate-Body Leakage Current, Forward	$V_{GS} = 30V, V_{DS} = 0V$	--	--	100	nA
$I_{GSSR}$	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	--	--	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.5	--	4.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS} = 10V, I_D = 5.5A$	--	0.46	0.5	$\Omega$
$g_{FS}$	Forward Trans conductance	$V_{DS} = 40V, I_D = 11A$	--	10	--	S
$R_g$	Gate resistance	f=1MHz,open drain	--	3	--	$\Omega$
Dynamic Characteristics						
$C_{iss}$	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V, f = 1.0MHz$	--	630	--	pF
$C_{oss}$	Output Capacitance		--	180	--	pF
$C_{rss}$	Reverse Transfer Capacitance		--	11	--	pF
$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 400V, I_D = 5.5A$ $R_G = 20\Omega$ (Note 4)	--	28	--	ns
$t_r$	Turn-On Rise Time		--	19	--	ns
$t_{d(off)}$	Turn-Off Delay Time		--	65	--	ns
$t_f$	Turn-Off Fall Time		--	19	--	ns
$Q_g$	Total Gate Charge	$V_{DS} = 480V, I_D = 5.5A$ $V_{GS} = 10V$ (Note 4)	--	13	--	nC
$Q_{gs}$	Gate-Source Charge		--	3.4	--	nC
$Q_{gd}$	Gate-Drain Charge		--	4.9	--	nC
Drain-Source Diode Characteristics and Maximum Ratings						
$I_s$	Maximum Continuous Drain-Source Diode Forward Current	--	--	11	A	
$I_{SM}$	Maximum Pulsed Drain-Source Diode Forward Current	--	--	30	A	
$V_{SD}$	Drain-Source Diode Forward Voltage	$V_{GS} = 0V, I_F = 5.5A$	--	0.9	1.5	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0V, I_F = 5.5A$ $dI_F/dt = 100A/\mu s$	--	270	--	ns
$Q_{rr}$	Reverse Recovery Charge		--	3.3	--	$\mu C$

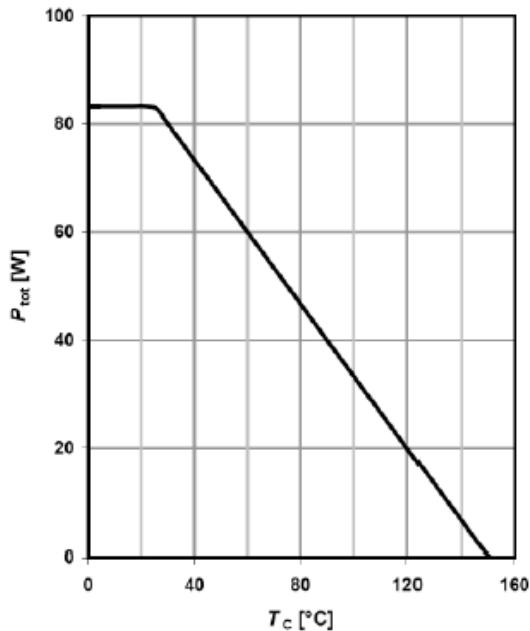
### NOTES:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2.  $I_{AS}=1.8A$ ,  $V_{DD}=50V$ , Starting  $T_J=25^\circ C$
3.  $I_{SD}\leq 10.5A$ ,  $dI/dt \leq 200A/\mu s$ ,  $V_{DD} \leq BV_{DSS}$ , Starting  $T_J = 25^\circ C$
4. Essentially Independent of Operating Temperature Typical Characteristics

# Typical Performance Characteristics

**1 Power dissipation**

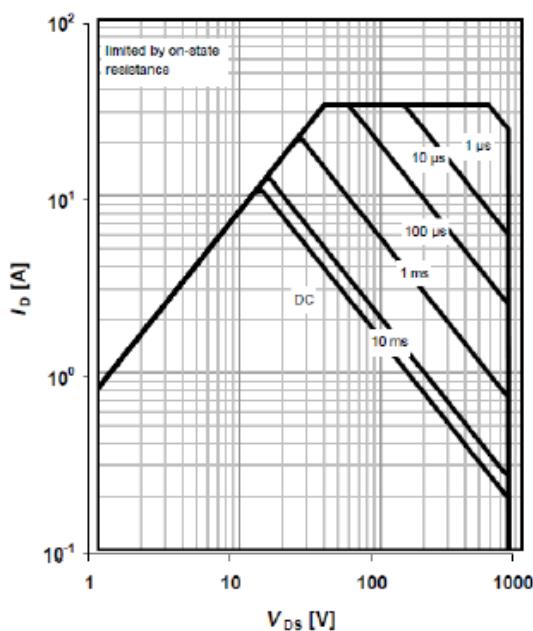
$$P_{\text{tot}} = f(T_c)$$



**2 Safe operating area**

$$I_D = f(V_{DS}); T_c = 25^\circ\text{C}; D = 0$$

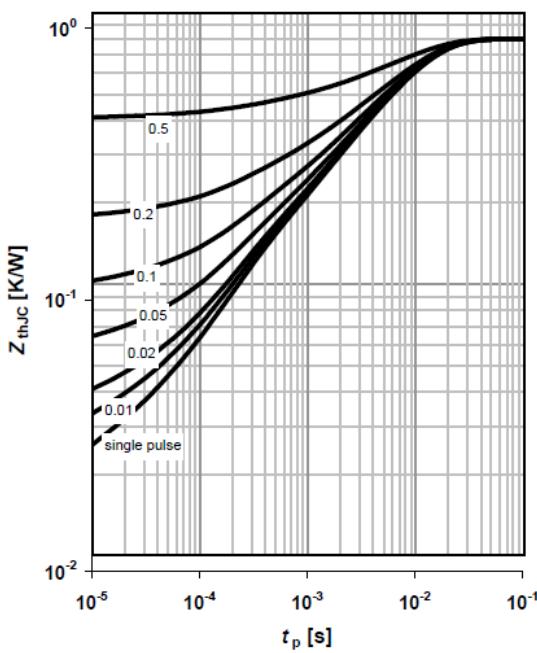
parameter:  $t_p$



**3 Max. transient thermal impedance**

$$Z_{\text{thJC}} = f(t_p)$$

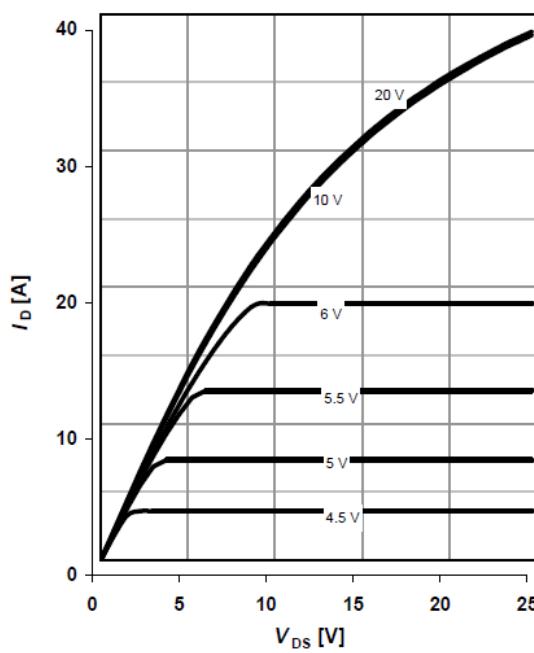
parameter:  $D = t_p/T$



**4 Typ. output characteristics**

$$I_D = f(V_{DS}); T_j = 25^\circ\text{C}; t_p = 10 \mu\text{s}$$

parameter:  $V_{GS}$

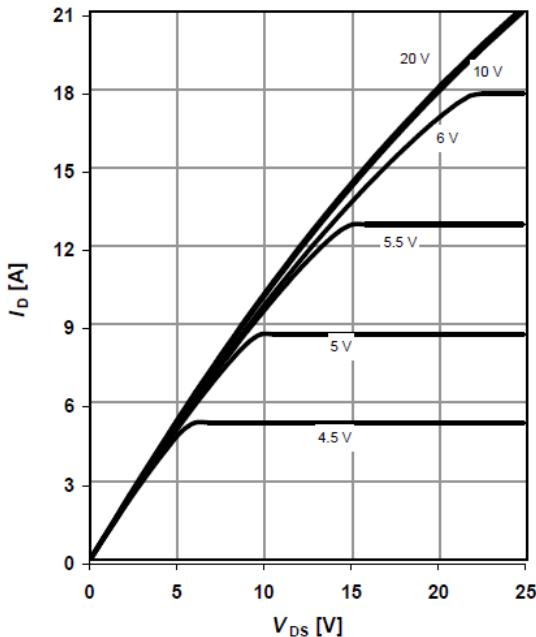


# Typical Performance Characteristics

5 Typ. output characteristics

$I_D=f(V_{DS})$ ;  $T_j=150\text{ }^\circ\text{C}$ ;  $t_p=10\text{ }\mu\text{s}$

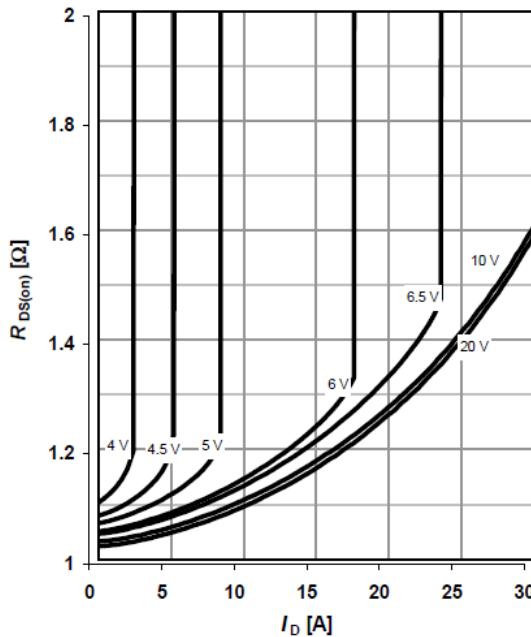
parameter:  $V_{GS}$



6 Typ. drain-source on-state resistance

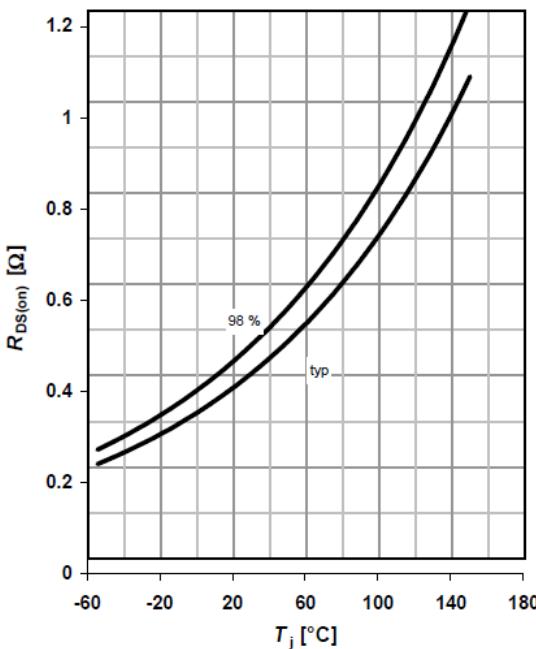
$R_{DS(on)}=f(I_D)$ ;  $T_j=150\text{ }^\circ\text{C}$

parameter:  $V_{GS}$



7 Drain-source on-state resistance

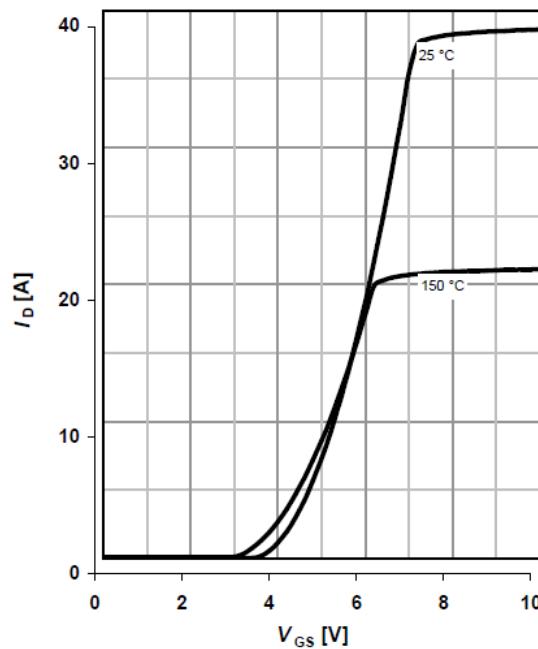
$R_{DS(on)}=f(T_j)$ ;  $I_D=7.1\text{ A}$ ;  $V_{GS}=10\text{ V}$



8 Typ. transfer characteristics

$I_D=f(V_{GS})$ ;  $|V_{DS}|>2|I_D|R_{DS(on)max}$ ;  $t_p=10\text{ }\mu\text{s}$

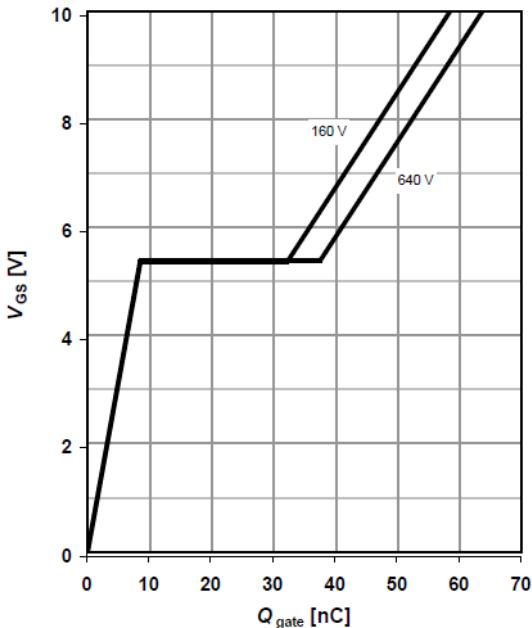
parameter:  $T_j$



# Typical Performance Characteristics

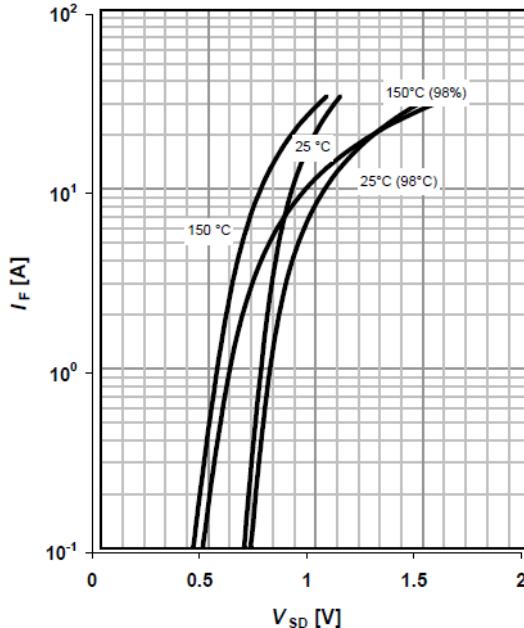
**9 Typ. gate charge**

$V_{GS}=f(Q_{gate})$ ;  $I_D=11\text{ A}$  pulsed  
parameter:  $V_{DD}$



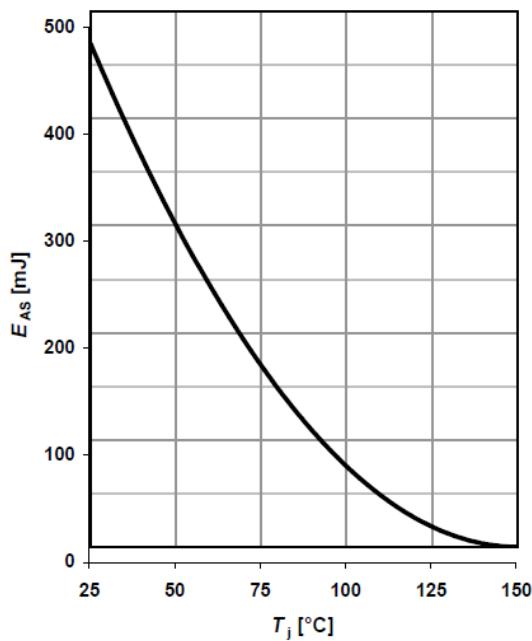
**10 Forward characteristics of reverse diode**

$I_F=f(V_{SD})$ ;  $t_p=10\text{ }\mu\text{s}$   
parameter:  $T_j$



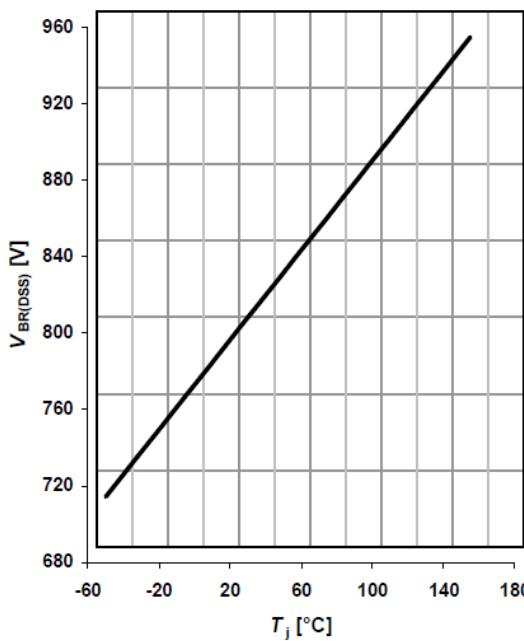
**11 Avalanche energy**

$E_{AS}=f(T_j)$ ;  $I_D=2.2\text{ A}$ ;  $V_{DD}=50\text{ V}$



**12 Drain-source breakdown voltage**

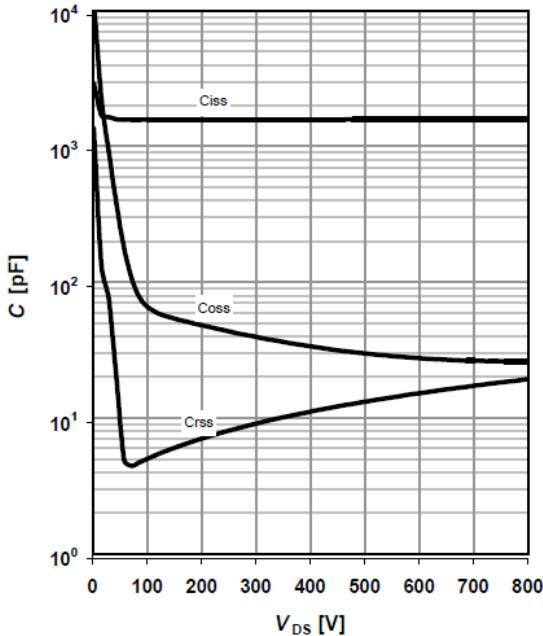
$V_{BR(DSS)}=f(T_j)$ ;  $I_D=0.25\text{ mA}$



# Typical Performance Characteristics

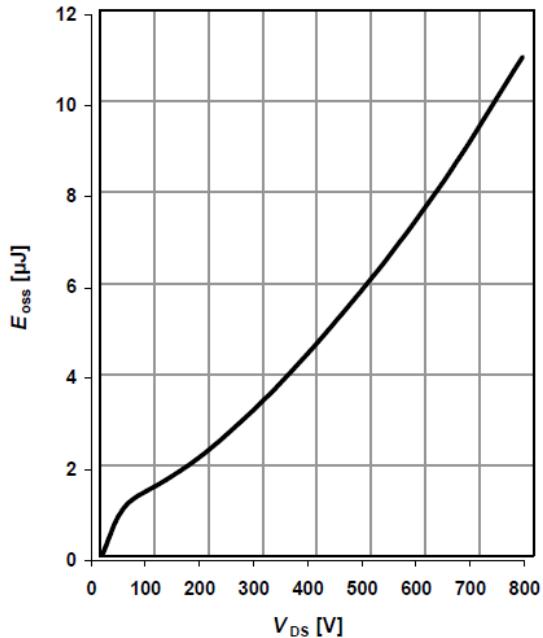
13 Typ. capacitances

$C = f(V_{DS})$ ;  $V_{GS} = 0$  V;  $f = 1$  MHz



14 Typ. Coss stored energy

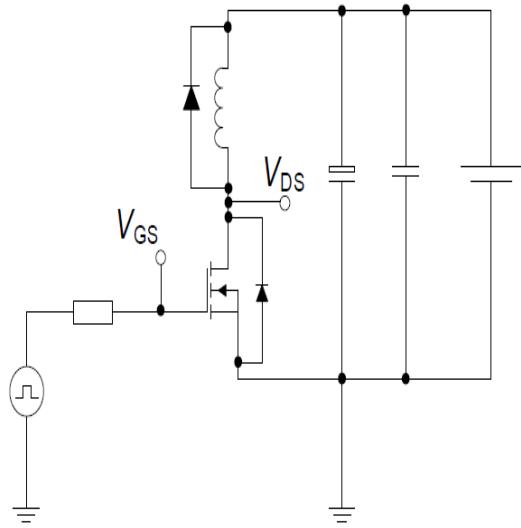
$E_{oss} = f(V_{DS})$



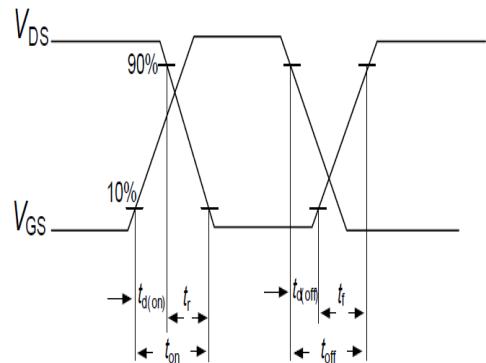
# Test circuits

## Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

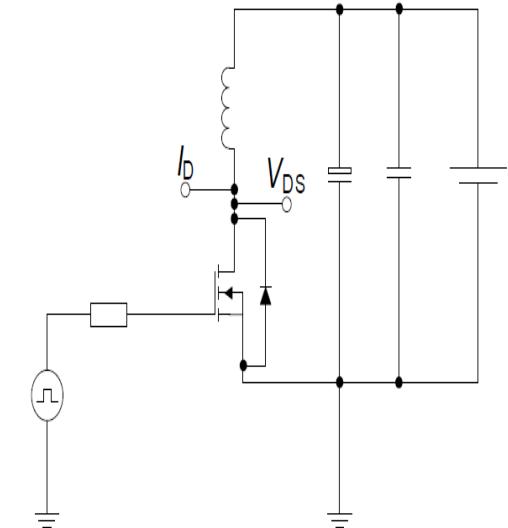


Switching time waveform

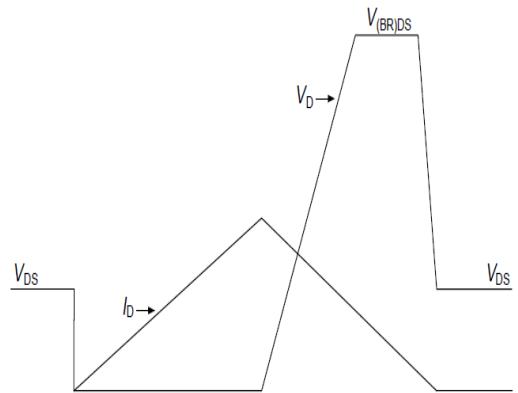


## Unclamped inductive load test circuit and waveform

Unclamped inductive load test circuit



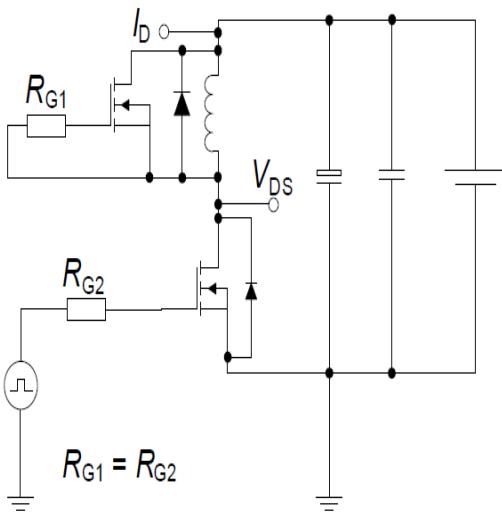
Unclamped inductive waveform



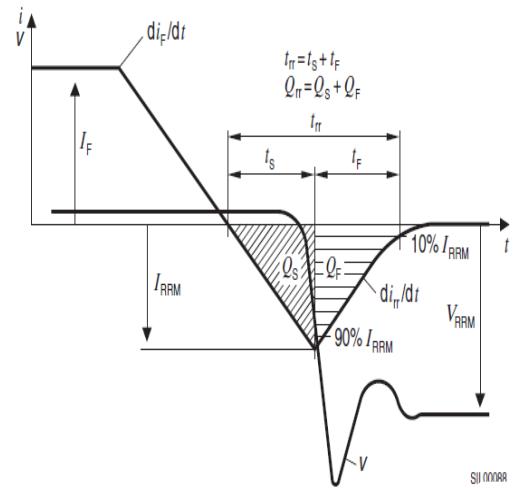
# Test circuits

## Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

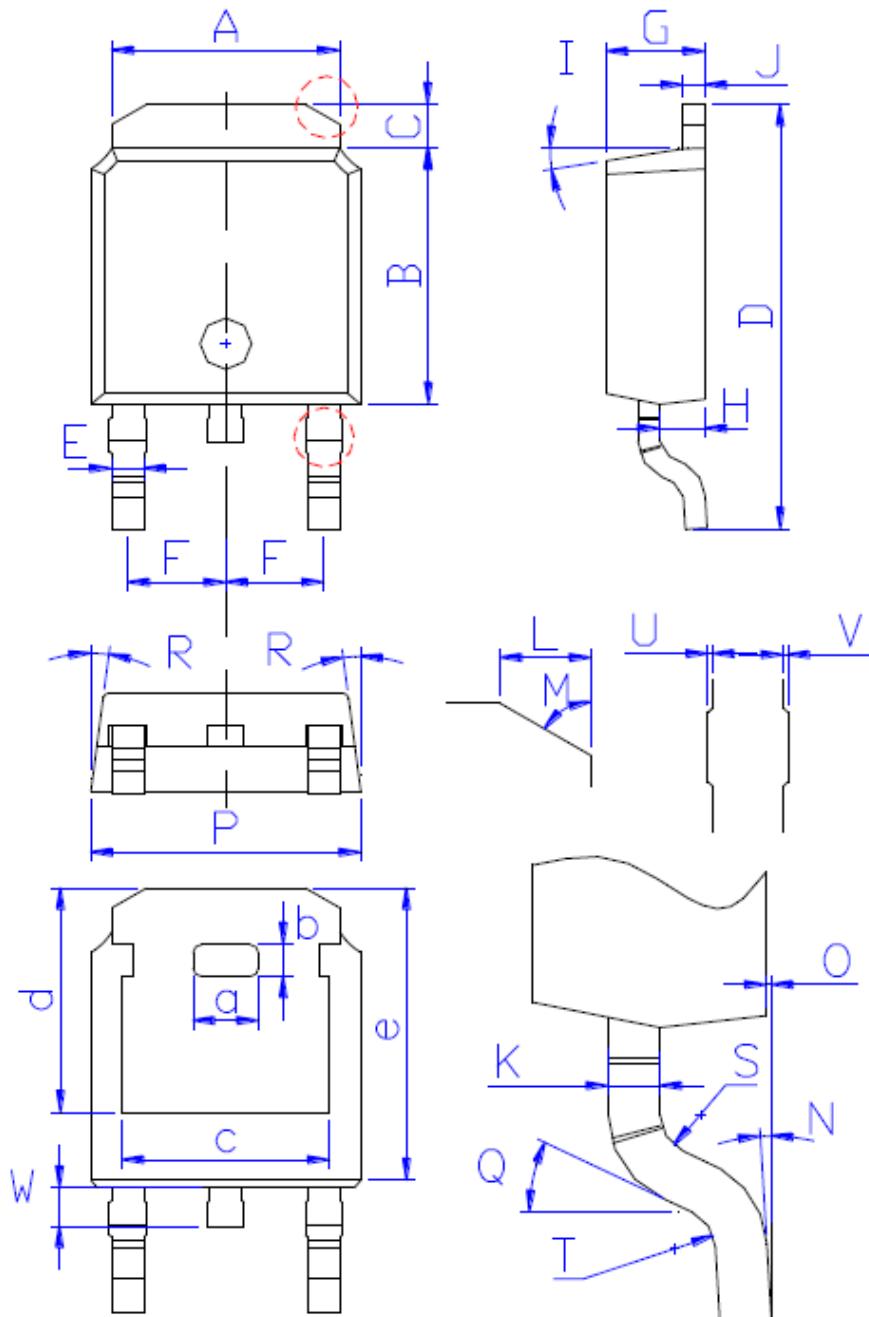


Diode recovery waveform



# Package Outline TO-252

TSD80R500S1 800V 10.5A N-Channel SJ-MOSFET



DIM	MILLIMETERS
A	5.34±0.30
B	6.00±0.30
C	1.05±0.30
D	9.95±0.30
E	0.76±0.15
F	2.28±0.15
G	2.30±0.30
H	1.06±0.30
I	(4-10)°
J	0.51±0.15
K	0.52±0.15
L	0.80±0.30
M	60°
N	(0-10)°
O	0.05±0.05
P	6.60±0.30
Q	25°
R	(4-8.5)°
S	R0.40
T	R0.40
U	0.05±0.05
V	0.05±0.05
W	0.90±0.30
a	1.80±0.30
b	0.75±0.30
c	4.85±0.30
d	5.30±0.30
e	6.90±0.30